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Preliminary News Release

**GE & FLEXCEED Collaborate to Develop
Next-Generation Packaging Solution Based on Polyimide Film Substrates**

NISKAYUNA, NY USA & IBARAKI, JAPAN – 24th of October, 2017 – GE Ventures and FLEXCEED Co., Ltd. (FLEXCEED) announced that FLEXCEED has been granted a patent license and technology transfer of a next-generation packaging solution based on polyimide film substrates embedded with electronic components for power electronics called Power OverLay (POL)*¹. This license and technology transfer deal, signed in February, 2017, is a strategic collaboration between GE and FLEXCEED in both technology and business development. Detailed information about launching POL business will be advised at a later date.

*¹ POL is a “chips first” packaging solution on polyimide film substrates with embedded semiconductor ICs and electric components, interconnected by copper plating. POL can significantly reduce resistance compared to traditional semiconductor modules with its smaller form factor and can result in higher efficiency of power conversion.

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